

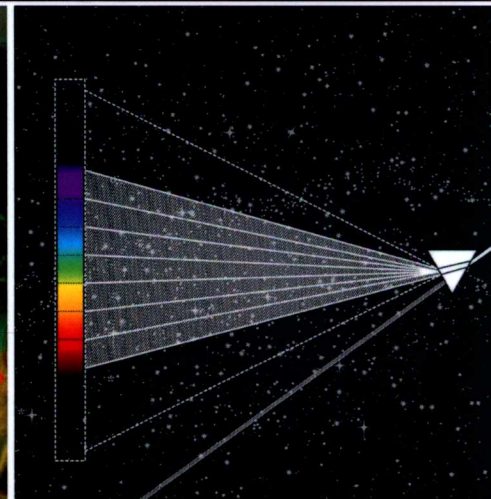
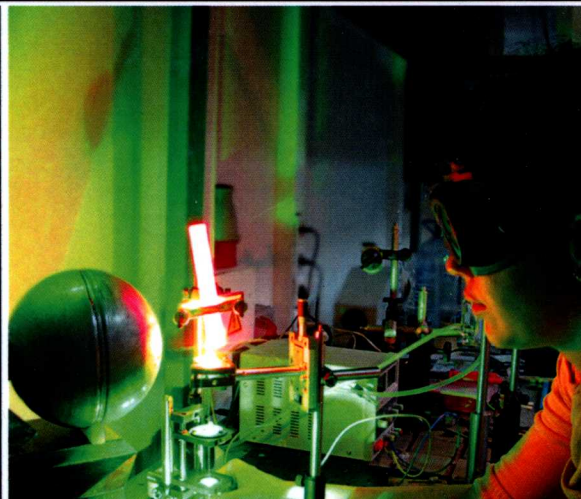
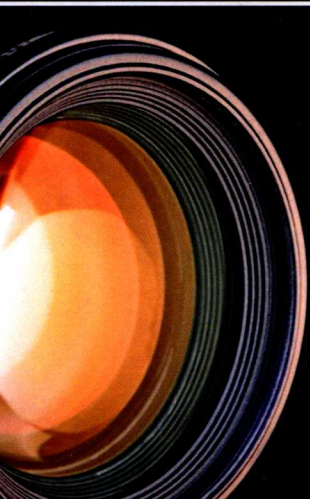
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Lidar—Optical Design

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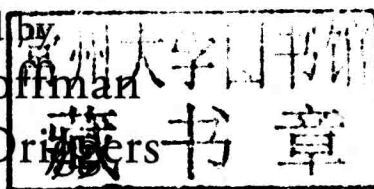
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6000 Broken Sound Parkway NW, Suite 300
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Printed on acid-free paper
Version Date: 20150803

International Standard Book Number-13: 978-1-4398-5110-4 (Hardback)

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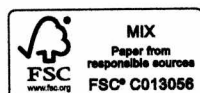
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